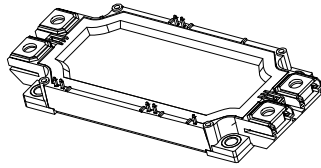


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

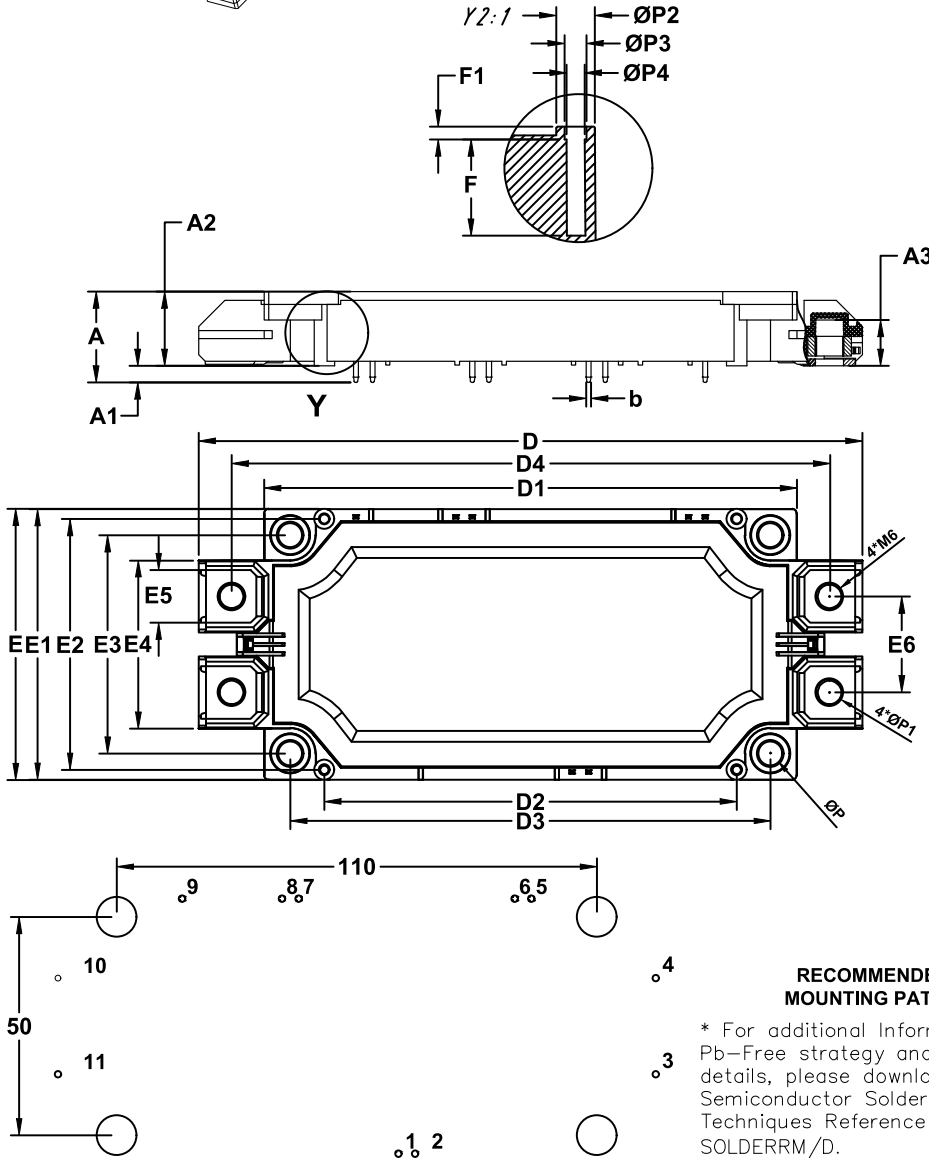


PIM11, 152.00x62.15x17.00
CASE 180HT
ISSUE C

DATE 11 MAR 2024

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5-2018.
- CONTROLLING DIMENSION : MILLIMETERS
- DIMENSIONS b AND b1 APPLY TO THE PLATED TERMINALS AND ARE MEASURED AT DIMENSION A1
- PIN POSITION TOLERANCE IS ± 0.4mm
- PACKAGE MARKING IS LOCATED AS SHOWN ON THE SIDE OPPOSITE THE PACKAGE ORIENTATION FEATURES
- SOLDER PIN



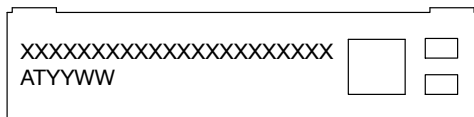
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	20.00	20.80	21.60
A1	3.50	3.80	4.10
A2	16.50	17.00	17.50
A3	10.00	10.5	11.00
A4	6.30	6.50	6.70
b	1.12	1.15	1.18
D	151.5	152.00	152.50
D1	121.50	122.00	122.50
D2	94.30	94.50	94.70
D3	109.80	110.00	110.20
E	61.95	62.15	62.35
E1	61.80	62.00	62.20
E2	57.30	57.50	57.70
E3	49.80	50.00	50.20
E4	38.40	38.60	38.80
E5	11.80	12.00	12.20
F	11.00	11.00	11.20
F1	1.40	1.45	1.50
P	5.20	5.50	5.60
P1	6.40	6.40	6.60
P2	4.45	4.65	4.85
P3	2.40	2.50	2.50
P4	2.05	2.10	2.10
D4	136.40	137.00	137.60
E6	21.60	22.00	22.40

Pin table			
Pin	X	Y	Function
1	9.52	-29.2	T2
2	13.33	-29.2	DC-
3	68.5	-11.0	DC-
4	68.5	11.0	DC+
5	40.0	29.2	TH2
6	36.19	29.2	TH1
7	-13.33	29.2	T1
8	-17.14	29.2	AC
9	-40.0	29.2	DC+
10	-68.5	11.0	AC
11	-88.5	-11.0	AC

RECOMMENDED MOUNTING PATTERN

* For additional Information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERM/D.

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
AT = Assembly & Test Site Code
YYYYW = Year and Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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